



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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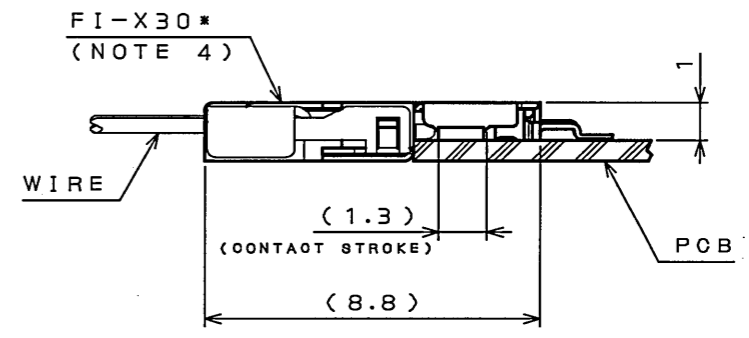
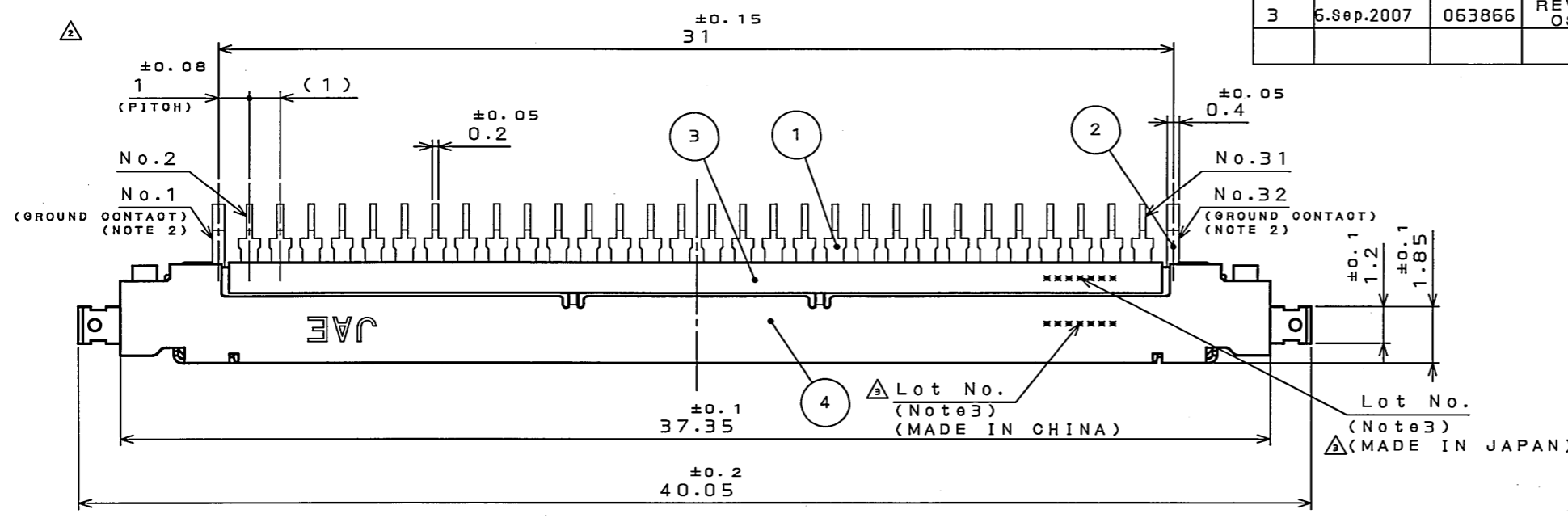
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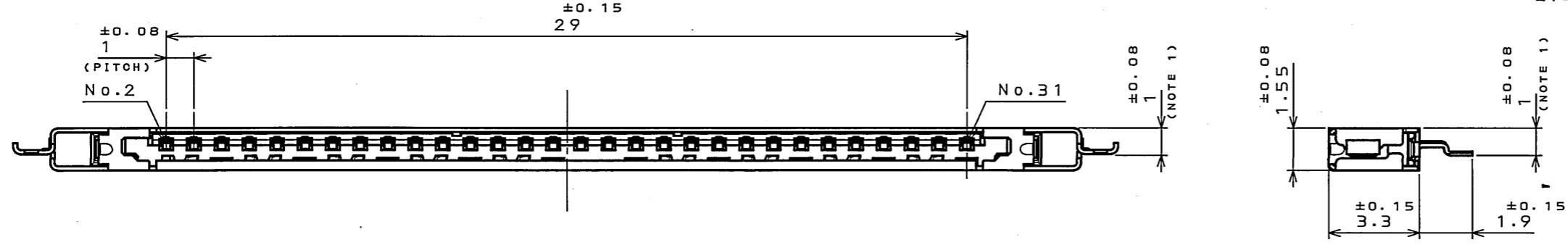


8Z6901RS
(ON 0NIMVHD) 台架型図

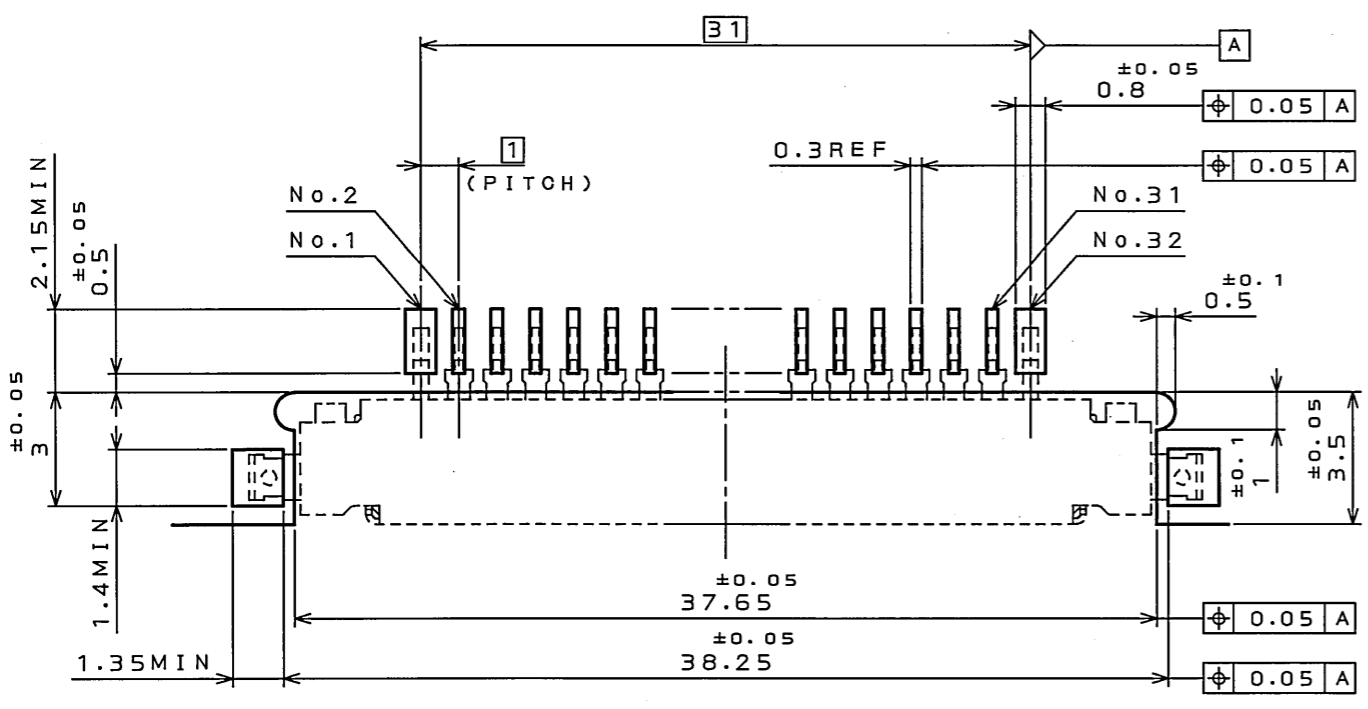
版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	12.Jan.2007	062001	REVISED FORM		T.YAMAJI	M.SUZUKI	K.HISATOMI
3	6.Sep.2007	063866	REVISED LOT NO. POSITION		T.YAMAJI	M.SUZUKI	K.HISATOMI



MATED CONDITION (REF.)
嵌合状態図 (参考)



- NOTE1. COPLANARITY BETWEEN TERMINAL AND HOLD DOWN OF SHELL SHOULD BE 0.1mm MAX.
 2. TERMINALS NO.1 AND NO.32 ARE APPROPRIATE FOR GROUND CONTACTS.
 3. PRODUCTION LOT NUMBER AS INDICATED.
 4. FOR INSPECTION, FI-X30HJ-B(SJ101192) IS RECOMMENDED.
- 注1. 端子及び、シェルのホルドダウンの相互のバラツキは0.1以内である。
 2. 端子No. 1及び32はグランド専用コンタクトとする。
 3. 図示の位置にロット番号を表示する。
 4. 検査用として使用の場合はFI-X30HJ-B(SJ101192)を推奨する。



APPLICABLE P.C.B. DIMENSION (REF.)
適合基板寸法 (参考)

符号 NO.	名称 DESCRIPTION	数量 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	SHELL	1	STAINLESS STEEL	TIN PLATING	
3	INSULATOR	1	HEAT RESISTING PLASTIC		UL94 V-0 BEIGE
2	GROUND PLATE	1	COPPER ALLOY	TIN PLATING	
1	CONTACT	30	COPPER ALLOY	GOLD(0.3μmMIN) OVER NICKEL	TERMINAL AREA: TIN OVER NICKEL

仕様書 (SPECIFICATION) JACS-10388	第1版 (ORIGINAL DATE) 4.Sep.2006	尺度 (SCALE) 5:1	シリーズ (SERIES) FI-X
公差 (GENERAL TOLERANCE)	製図 (DRAWING) DR.	名称 (TITLE) FI-XPB30SL-HF10 (BOTTOM TYPE)	
寸法 (DIMENSION) 角度 (ANGLES)	担当 (CHECKER) CHK. T.YAMAJI	日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.	
	査閲 (APPROVER) APPD. M.SUZUKI		
	承認 (APPROVER) APPD. K.HISATOMI		
		質量 (MASS)	図面番号 (DRAWING NO.) SJ106928

LEAD FREE この製品は鉛フリー品です

DOF-0-212F(05.08)

